PCN Number: 201706		70615	615006A			P	CN Date:	Sept. 6, 2017		
Title	Fitle: Qualification of Ad			Addit	dditional Assembly site for select Devices					
Customer PCN Man		Aanade	ar	Dont	Quality Consid					
Cont			PCN /V	nariage	<u>=1</u>	Dept:	Quality Service	.es		
Proposed 1 st Ship Sate:		Sept	t. 19, 2017	Estim	ated Sample A	vaila	vailability: Provided upor Request			
Chan	ige Ty	pe:		•						
		mbly Site			Assembly Process				Assembly Materials	
	Desig	jn .				Specificat	tion		Mechanical Specification	
	Test	Site			Packing/	Shipping/L	abeling		Test Process	
	Wafe	r Bump Si	ite		Wafer Bu	ımp Mater	ial		Wafer Bump Process	
	Wafe	r Fab Site			Wafer Fa	b Material	S [Wafer Fab Process	
					Part num	ber chang	е			
						PCN Det	ails			
Desc	riptio	n of Cha	nge:							
							that were not in			
							olded in the de			
			or thes	se nev	w devices w	ill be 90 d	ays from this no	tice f	for these n	ewly added
devic	es onl	<mark>У.</mark>								
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							ation of PTI as a			
	nbly s		ow. i	nere	are no sign	ilicalit ulli	erences in device	es bu	ilit betweel	i tile two
assei	libly 5	ites.								
Reas	on fo	r Change	:							
Conti	nuity	of Supply								
Anticipated impact on Fit, Form, Function, Quality or Reliab				ty or Reliability	(pc	sitive / n	egative):			
None										
Antic	cipate	d impact	on M	ateri	al Declara	tion				
No Impact to		Material Declarations or Product Content reports are driven from								
the Material		production data and will be available following the production release.								
Declaration		Upon production release the revised reports can be obtained from the								
					<u>ΓΙ ECO web</u>	<u>site</u> .				
Chan	iges t	o produc	t iden	tifica	ation resul	ting from	this PCN:			
		Assembly Site Assem		embly Site Origin (22L)		L) Assemb	embly Country Code (2		Asse	embly City
	Assemb				JJN		TWN		NEW ⁻	TAIDEL CITY
	Jor	Jin								TAIPEI CITY
		Jin			אונו PT2		TWN		HSIN	CHU CITY
	Jor	Jin					TWN		HSIN	
	Jor	Jin					TWN		HSIN	
	Jor	Jin					TWN		HSIN	
	Jor	Jin					TWN		HSIN	
	Jor	Jin					TWN		HSIN	
	Jor	Jin					TWN		HSIN	
	Jor	Jin					TWN		HSIN	

Sample product shipping label (not actual product label)



OPT: ITEM:

(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483SI2

(2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS

Topside Device marking (if included):

Assembly site code for JJN= T

Assembly site code for PT2 = C

5A (L)T0:1750

Product Affected			
WL1801MODGBMOCR	WL1805MODGBMOCT	WL1831MODGBMOCT	WL1837MODGIMOC
WL1801MODGBMOCR-WI	WL1807MODGIMOCR	WL1835MODGBMOCR	WL1837MODGIMOCR
WL1801MODGBMOCT	WL1807MODGIMOCT	WL1835MODGBMOCT	WL1837MODGIMOCT
WL1805MODGBMOCR	WL1831MODGBMOCR		



TI Information Selective Disclosure

Qualification Report

WL1835 MODULE - 2nd Source Plan - Assy site PTI

This Qualification report qualifies WL1801MOD, WL1805MOD & WL1835MOD for PTI Assembly

Product Attributes

Attributes	Qual Device: WL1835MODGBMOC	QBS Device: WL1837MODGIMOC		
Assembly Site	PTI	PTI		
Package Family	Module	Module		

⁻ QBS: Qual By Similarity

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: WL1835MODGBMOC	QBS Device: WL1837MODGIMOC
PC	Preconditioning Level 3	MSL3, 260C reflow	1/50/0	1/230/0
TC	Temperature Cycle, -40/105	500cy	1/45/0	1/45/0
UHAST	Unbiased Temperature and Humidity, 85C/85%RH	500hr		1/45/0
LTSL	Low Temperature Storage Bake -40C	500hr		1/45/0
HTSL	High Temperature Bake 105C	500hr		1/45/0
VVF	Vibration Variance Frequency	20 - 2000 - 20 Hz Log sweep		1/5/0
CDM	ESD CDM	500V	1/3/0	1/3/0
HBM	ESD HBM	1000V	1/3/0	1/3/0

Preconditioning was performed for Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

⁻ Qual Device is qualified at MSL LEVEL3-260C

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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